WHAT IS CLAIMED IS:

An electronic device comprising:

an element carrying substrate having an electronic element and a first electrode, said first electrode disposed on a surface of said element carrying substrate and having a prescribed area;

a wiring substrate arranged to face said element carrying substrate and having a second electrode disposed on a surface of said wiring substrate, said second electrode having a prescribed area and facing said first electrode; and

a coupler disposed between said first electrode and said second electrode to join said element carrying substrate and said wiring substrate, said coupler having a resin body and an electroconductive member, the surface of said coupler comprising a resin region and an electroconductive region to thereby electrically connect said first electrode and said second electrode.

- 2. An electronic device as claimed in claim 1, wherein the resin region occupies from 20 to 80% of the surface area of the coupler.
- 3. An electronic device as claimed in claim 1, wherein the electroconductive member is formed from a joining metal and the electroconductive region is formed by the joining metal locating on the surface of the coupler.
 - 4. An electronic device as claimed in claim 1, wherein

the electroconductive member comprises metal powder with a high melting point and the electroconductive region is formed by the metal powder locating on the surface of the coupler, the metal powder having a joining metal film joined thereto.

- 5. An electronic device as claimed in claim 1, wherein the electroconductive member comprises a metal strip layer having a joining metal film joined thereto, the metal strip layer encircling the resin body to thereby form the electroconductive region.
- 6. An electronic device as claimed in claim 5, wherein the metal strip layer has an opening disposed substantially at a center of the element carrying substrate and the wiring substrate.
- 7. An electronic device as claimed in claim 1, wherein the resin body is formed from a thermosetting resin.
- 8. An electronic device as claimed in claim 1, wherein the resin body is formed from a thermoplastic resin.
- 9. A coupler with a spherical shape comprising a blend of a joining metal and a resin, wherein the surface of said coupler comprises an electroconductive region formed by the joining metal an a resin region formed by the resin.
- 10. A coupler with a spherical shape comprising a resin body and metal powder with a high melting point, the surface of the coupler comprising an electroconductive region and a resin region, wherein the metal powder locating on the surface

of the coupler has a joining metal film joined thereto to form the electroconductive region.

11. A coupler with a spherical shape comprising a resin ball and a metal strip layer, the metal strip layer encircling the resin body and having an opening, wherein the metal strip layer has a joining metal film joined thereto.